

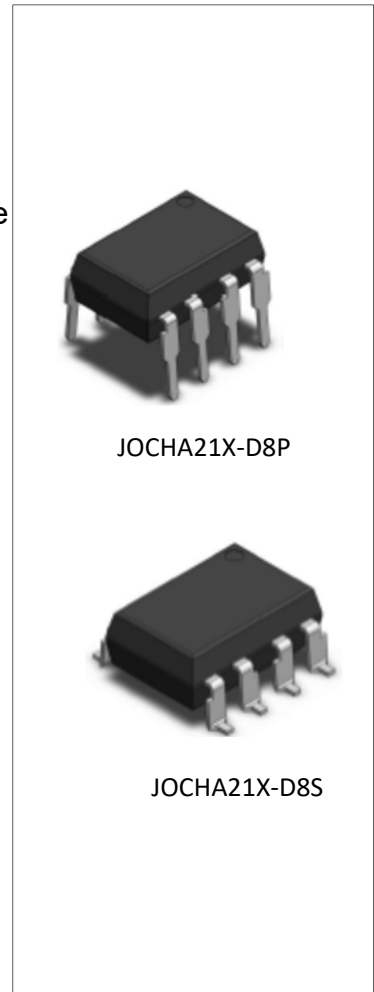


## JOCHA21X-D8P/S Series

Rev.A.1.0

### DESCRIPTION:

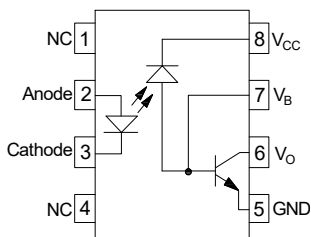
The products are 1MBd high-speed opto-couplers. The device is a small-outline coupler suitable for surface-mount assembly. It consists of a high-output-power infrared LED optically coupled to a high-speed photodiode-transistor chip. It is housed in a plastic DIP8 package with different lead forming options package and guarantees a creepage distance of  $\geq 5$  mm, a clearance of  $\geq 5$  mm and an insulation thickness of  $\geq 0.4$  mm. Therefore, it meets the reinforced insulation class requirements of international safety standards. The products are widely used in programmable controllers, industrial inverters and switching power supplies.



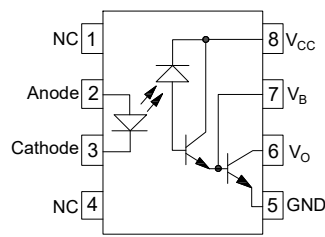
### MAIN FEATURES

- High isolation 5000 VRMS
- High speed – 1MBd typical
- Operating temperature range -40°C to 110°C
- REACH & RoHS compliance
- HBM: H3A; MM: M4; CDM: C3
- CQC approved
- VDE approved
- UL approved

### Schematic



**JOCHA21B-D8P/S**



**JOCHA21E-D8P/S**

Note: Vb Default NC

### Truth Table

LED	Output
ON	L
OFF	H

**ABSOLUTE MAXIMUM RATINGS** (Temperature=25°C)

Parameter		Symbol	Value	Unit
Input	Forward Current	$I_F$	50	mA
	Peak Forward Current	$I_{FP}$	1 <sup>①</sup>	A
	Reverse Voltage	$V_R$	6	V
	Input Power Dissipation	$P_D$	100	mW
Output	Supply Voltage	$V_{CC}$	35	V
	Output Voltage	$V_O$	20	V
	Output Current	$I_O$	8	mA
	Output Power Dissipation	$P_O$	100	mW
Total Power Dissipation		$P_{tot}$	200	mW
Isolation Voltage		$V_{iso}$	5000 <sup>②</sup>	Vrms
Operating Temperature		$T_{opr}$	-40~110	°C
Junction Temperature		$T_j$	125	°C
Storage Temperature		$T_{stg}$	-55~125	°C
Soldering Temperature		$T_{sol}$	260	°C

**NOTE1** : 100μs pulse, 100Hz frequency

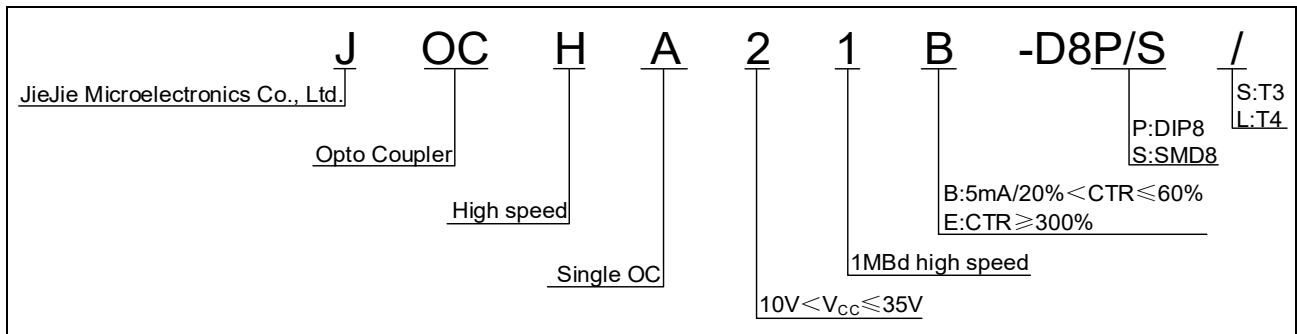
**NOTE2** : AC for 1minute, R.H.=40~60%

**ELECTRICAL CHARACTERISTICS** (Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit	
Input	Forward Voltage	$V_F$	$I_F=10mA$	-	1.35	1.6	V	
	Reverse Current	$I_R$	$V_R=6V$	-	-	1	μA	
	Input Capacitance	$C_{in}$	$V=0, f=1MHz$	-	60	-	pF	
Output	Current transfer ratio	CTR	B	$I_F=16mA, V_{CC}=4.5V,$ $V_O=0.4V$	20	-	60	%
			E		300	-	-	
	High Level Output Current	$I_{OH}$	$I_F=0mA, V_{CC}=5.5V,$ $V_O=5.5V$	-	3	500	nA	
			$I_F=0mA, V_{CC}=15V,$ $V_O=15V$	-	-	50	μA	
	Low Level Supply Current	$I_{CCL}$	$V_O=Open,$ $V_{CC}=15V,$ $I_F=16mA$	-	0.5	0.8	mA	
High Level Supply Current	$I_{CCH}$	$V_O=Open,$ $V_{CC}=15V,$ $I_F=0mA$	-	0.01	2	μA		

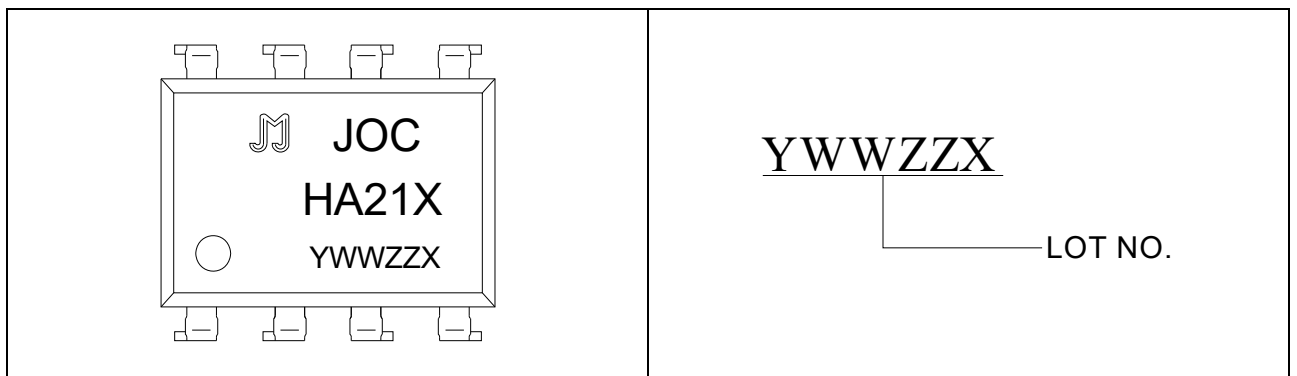
	Logic Low Output Voltage	$V_{OL}$	$I_F=16mA, I_O=2.4mA,$ $V_{CC}=4.5V$	-	-	0.4	V
	Isolation Resistance	$R_{ISO}$	DC500V 40~60%R.H.	$10^{12}$	$10^{14}$	-	$\Omega$
	Floating Capacitance	$C_{IO}$	$V=0, f=1MHz$	-	0.8	-	pF
Switching Characteristics	Propagation Delay Time to Logic Low	TPHL	$I_F=0 \rightarrow 16mA,$ $R_L=1.9k\Omega,$ $V_{CC}=5V$	-	-	0.8	$\mu s$
	Propagation Delay Time to Logic High	TPLH	$I_F=16 \rightarrow 0mA,$ $R_L=1.9k\Omega,$ $V_{CC}=5V$	-	-	0.8	$\mu s$
	Common Mode Transient Immunity at Logic High	CMH	$I_F=0mA,$ $V_{CM}=400V_{pp},$ $R_L=4.1k\Omega$	15	20	-	kV/ $\mu s$
	Common Mode Transient Immunity at Logic Low	CML	$I_F=16mA,$ $V_{CM}=400V_{pp},$ $R_L=4.1k\Omega$	-15	-20	-	kV/ $\mu s$

**ORDERING INFORMATION**



Packing Quantity	
Option	Quantity
DIP	50 Units/Tube
SMD	1200 Units/Reel

**MARKING**



Characteristics Curves

FIG.1: Forward Current vs. Forward Voltage

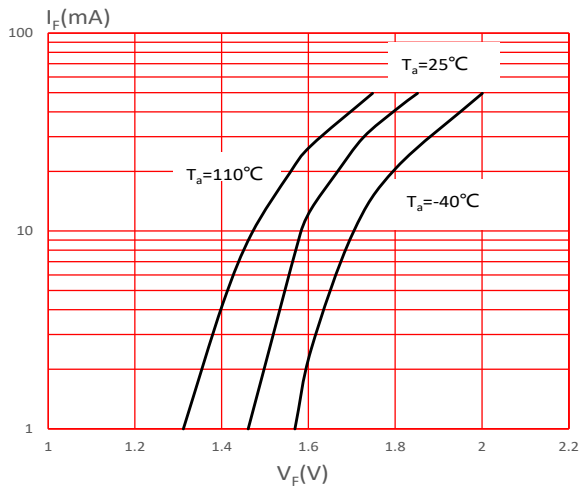


FIG.2: High Level Output Current vs. Ambient Temperature

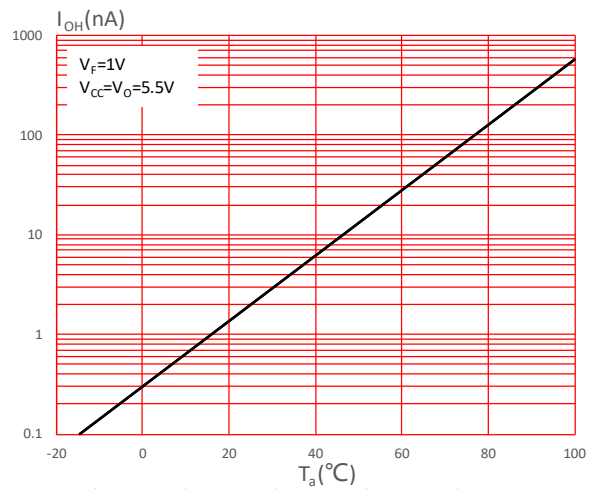


FIG.3: Output Current vs. Forward Current

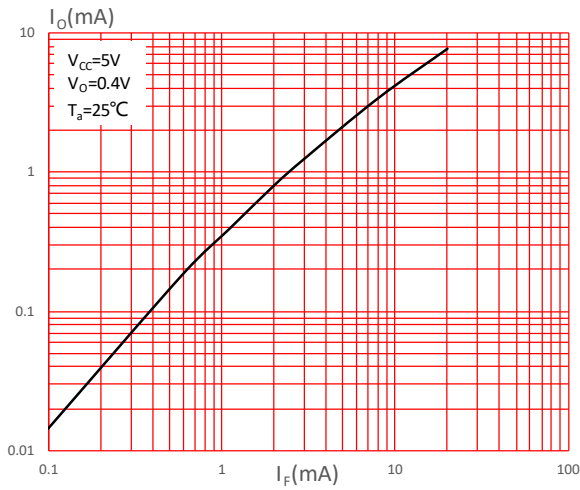


FIG.4: Normalized Current Transfer Ratio vs. Forward Current

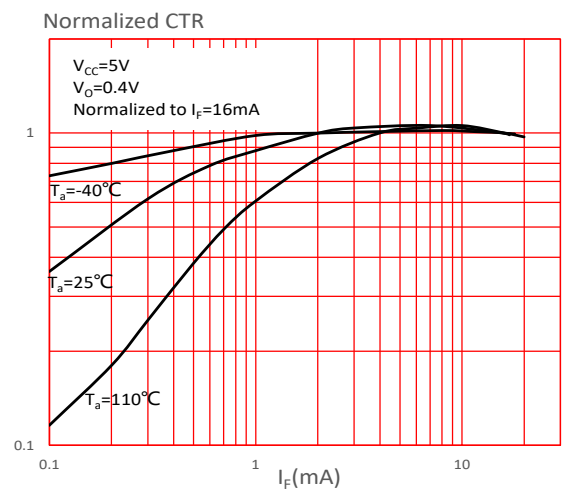


FIG.5: Normalized Current Transfer Ratio vs. Ambient Temperature

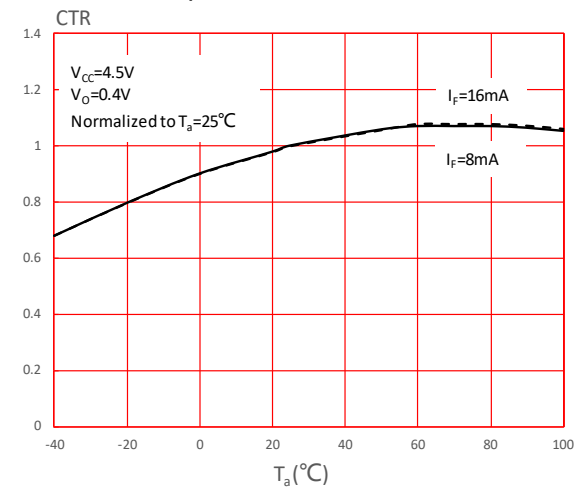
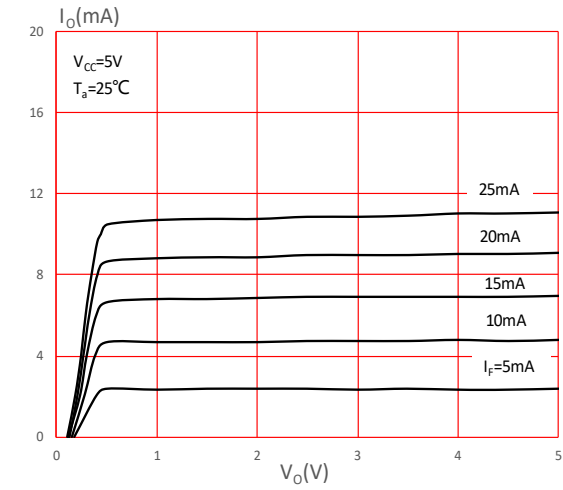
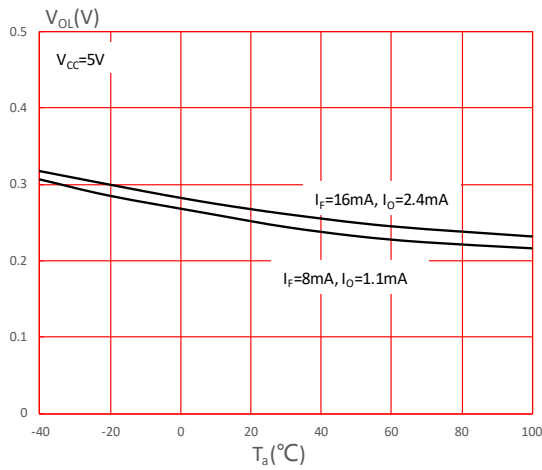


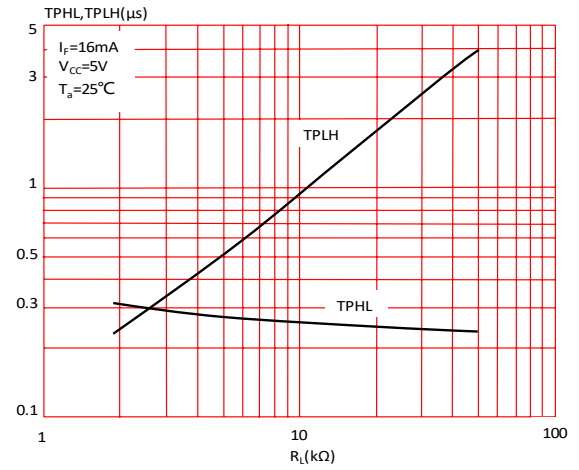
FIG.6: Output Current vs. Output Voltage



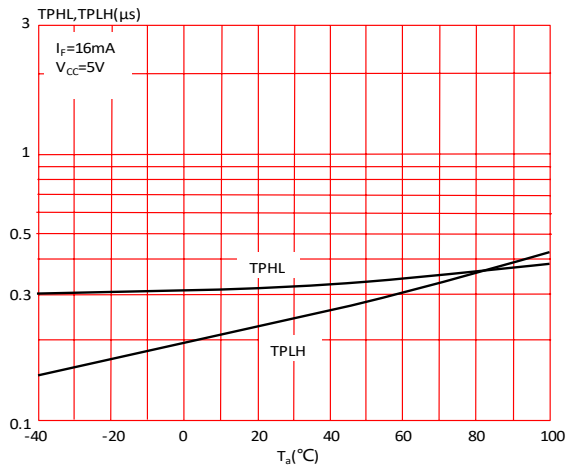
**FIG.7:** Low Level Output Voltage vs. Ambient Temperature



**FIG.8:** Propagation Delay vs. Load Resistance



**FIG.9:** Propagation Delay vs. Ambient Temperature



TEST CIRCUITS

Fig.10: Switching Time Test Circuit and Waveform

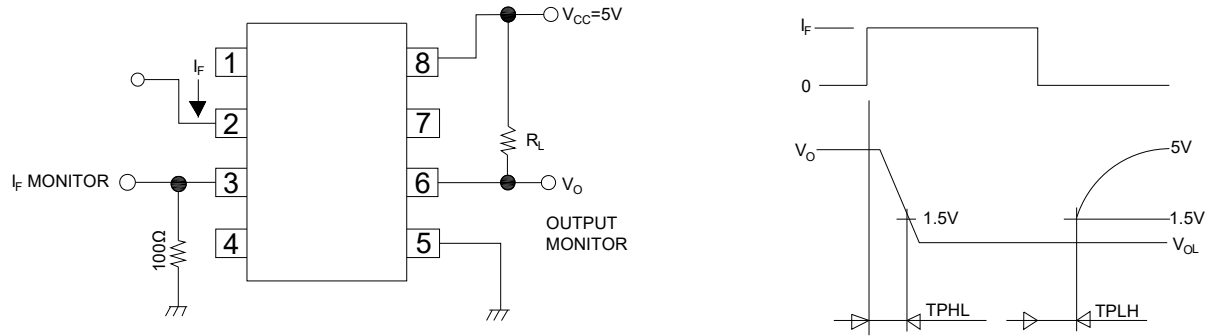
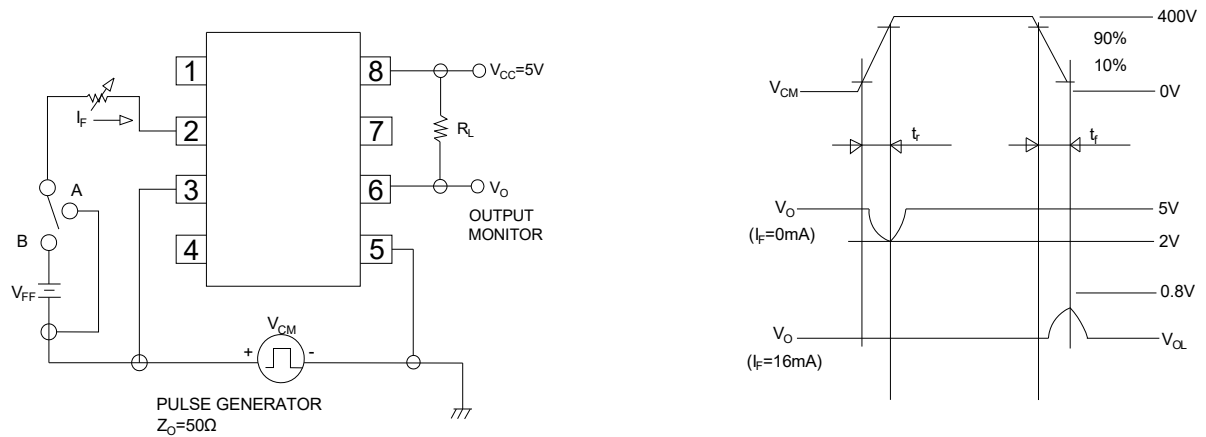
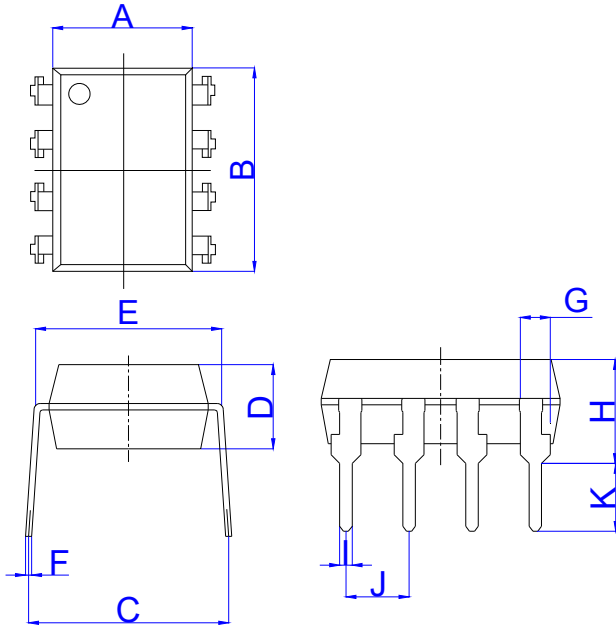


Fig.11: CMTI Test Circuit and Waveform



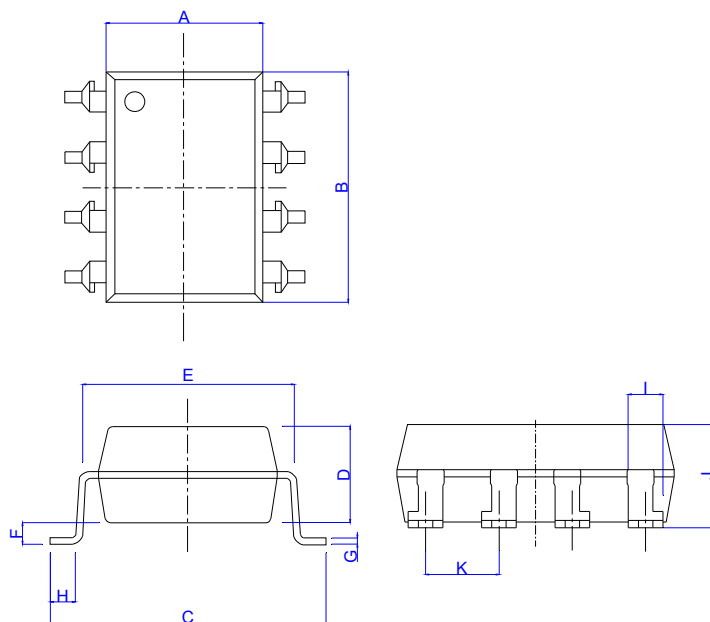
Package Dimension (Unit: mm)

Standard DIP Type:



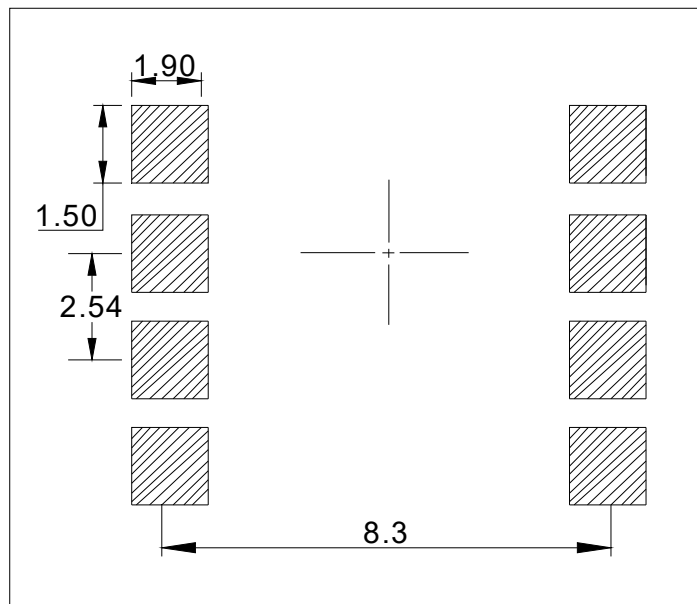
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	9.40		9.80	0.370		0.386
C	7.15		8.95	0.281		0.352
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.15		0.35	0.006		0.014
G	0.90		1.50	0.035		0.059
H	3.90		4.50	0.154		0.177
I	0.40		0.60	0.016		0.024
J	2.29		2.79	0.090		0.110
K	2.24		3.24	0.088		0.128

Option SMD Type:



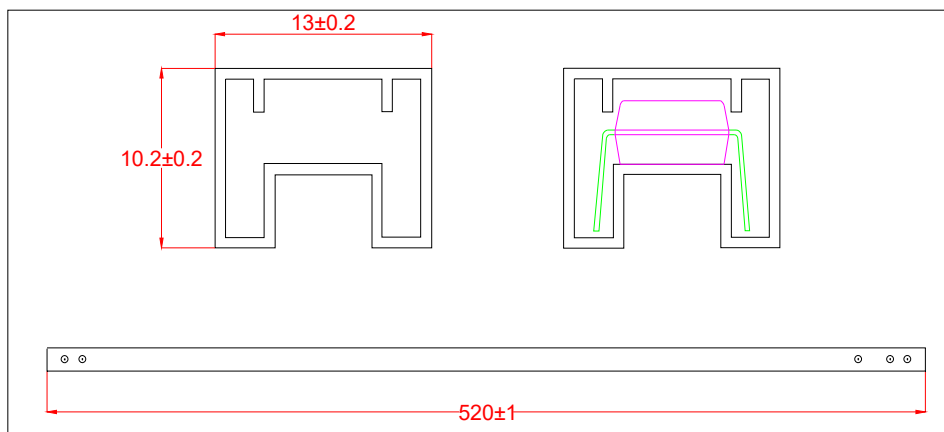
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	9.40		9.80	0.370		0.386
C	9.50		10.50	0.374		0.413
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.05		0.35	0.002		0.014
G	0.16		0.36	0.006		0.014
H	0.60		1.40	0.024		0.055
I	0.90		1.50	0.035		0.059
J	3.30		3.90	0.130		0.154
K	2.29		2.79	0.090		0.110

**RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)**



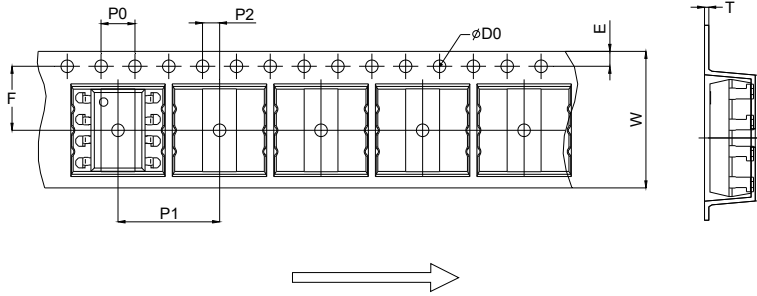
**TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)**

**Standard DIP**



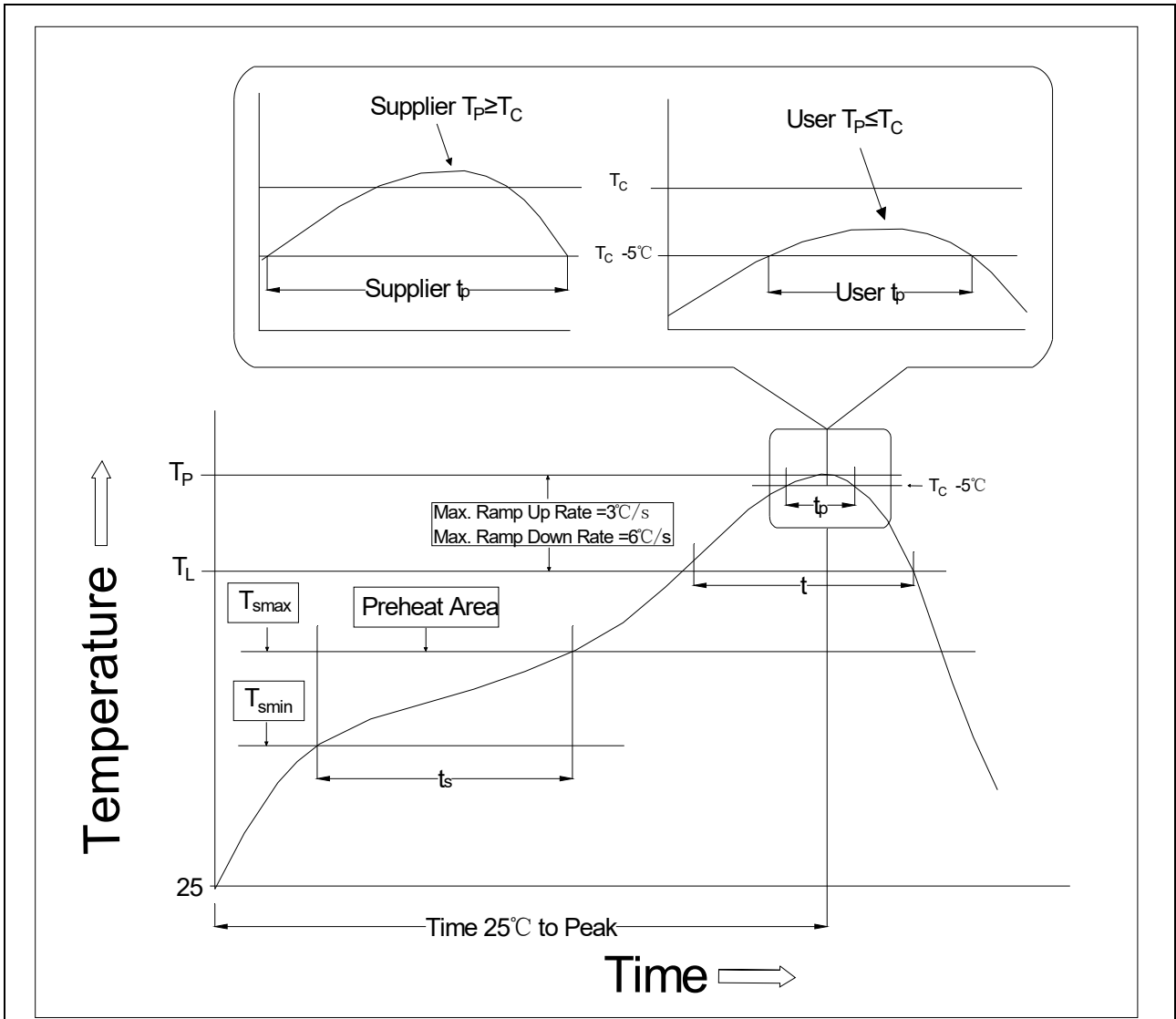
**CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)**

Option S/L



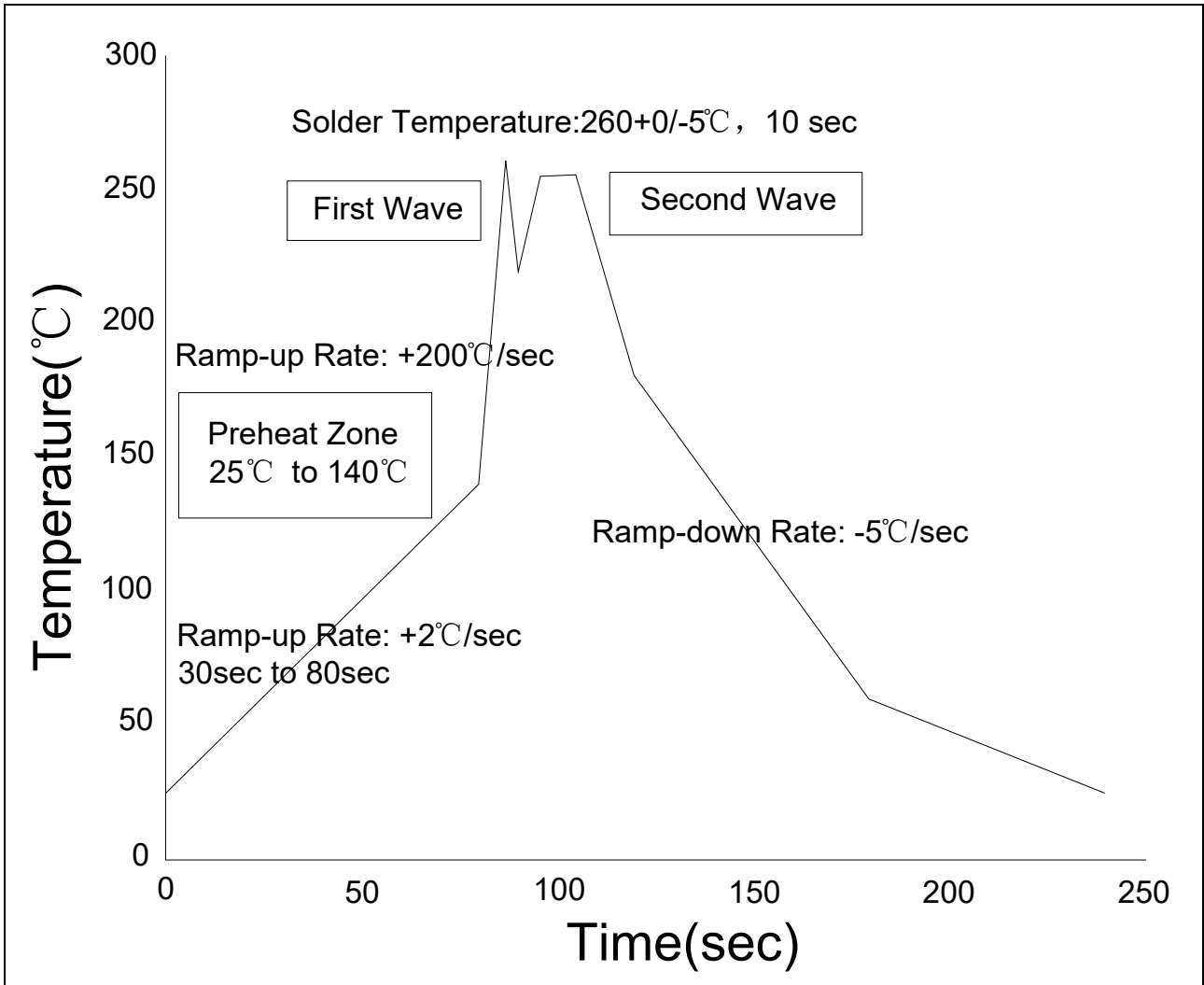
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.90	16.00	16.20	0.626	0.630	0.638

REFLOW INFORMATION



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T <sub>smin</sub> )	100	150°C
Temperature Max. (T <sub>smax</sub> )	150	200°C
Time (t <sub>s</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> )	60-120 seconds	60-120 seconds
Ramp-up Rate (t <sub>L</sub> to t <sub>P</sub> )	3°C/second max.	3°C/second max.
Liquidus Temperature (T <sub>L</sub> )	183°C	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235°C+0°C/-5°C	260°C+0°C/-5°C
Time (t <sub>P</sub> ) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

**WAVE SOLDERING**



**HAND SOLDERING BY SOLDERING IRON**

Soldering Temperature	$360 \pm 5^{\circ}\text{C}$
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;  
Recommend storage humidity: <60%;  
MSL level: MSL 1

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